



M14C32 DD

M14C32 Die Description

PRODUCT

M14C32

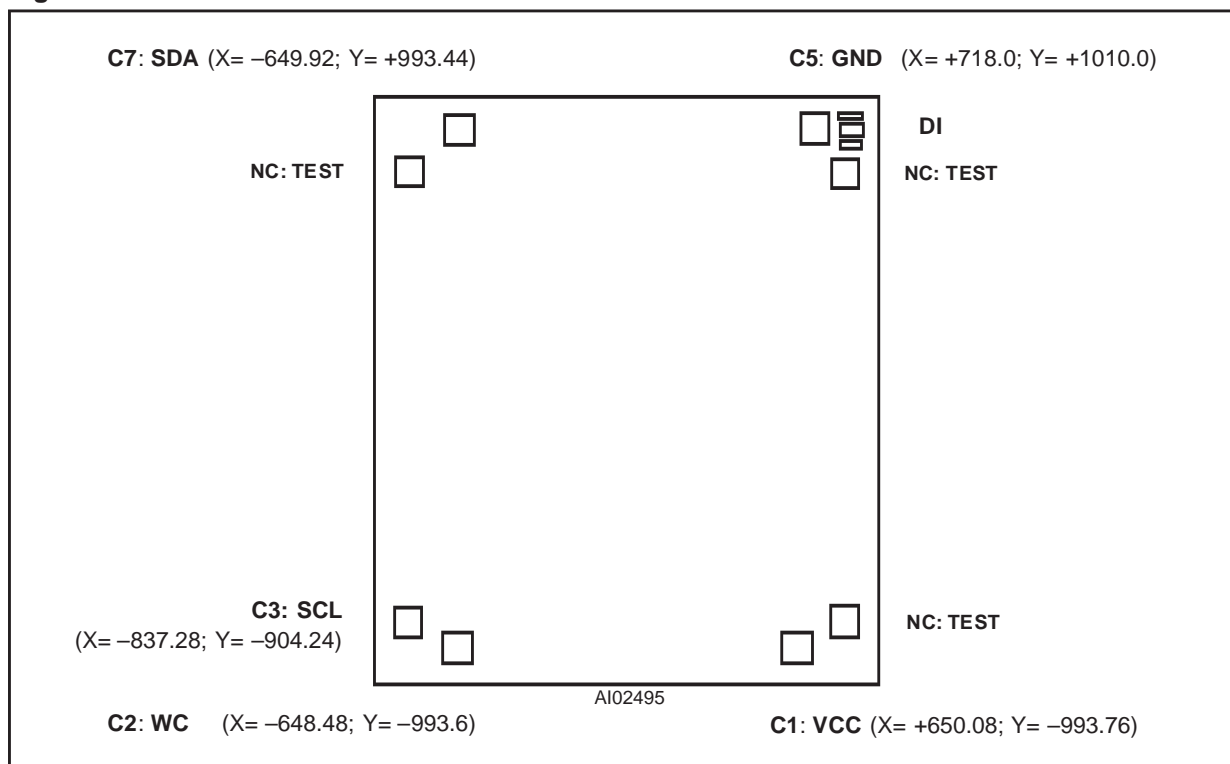
- WAFER SIZE 152 mm (6 inches)
- DIE IDENTIFICATION M14C32KA_R
- DIE SIZE (X x Y) 2040 x 2355 μm
- SCRIBE LINE 100.5 x 101.7 μm
- PAD OPENING 100 x 100 μm

DIE LAYOUT

- DI Die Identification (at the position shown in Figure 1)
- C1, C2, C3, C5, C7 Pad contacts to the ISO pins (at the positions shown in Figure 1)
- C4, C6, C8 These ISO pins do not appear on the M14C32 die
- NC This pad, shown in Figure 1, is Not Connected

Pad locations are measured relative to the die centre (where X and Y are respectively the horizontal and vertical axis, measured in μm).

Figure 1. M14C32 Die Plot



Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

© 1998 STMicroelectronics - All Rights Reserved

The ST logo is a registered trademark of STMicroelectronics.

All other names are the property of their respective owners.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - France - Germany - Italy - Japan - Korea - Malaysia - Malta - Mexico - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A.

<http://www.st.com>